Low-cost PDMS seal ring for single-side wet etching of MEMS structures

J. Brugger a,*, G. Beljakovic a,b, M. Despont a, H. Biebuyck a, N.F. de Rooij b, P. Vettiger a

a IBM Research Division, Zurich Research Laboratory, 8803 Rischlikon, Switzerland
b Institute of Microtechnology, University of Neuchâtel, 2000 Neuchâtel, Switzerland

Abstract

We describe a new O-ring setup for wet-etching processes of microelectromechanical systems (MEMS). Our new low-cost approach using siloxane-based seal rings entails the single-side etching of silicon and silicon dioxide using potassium hydroxide and buffered hydrofluoric acid, respectively. With this approach, the wafer is not immersed into the etching solution, but only the side to be etched is in contact with the solution, hence the previously fabricated device elements on the other side of the wafer are not damaged. In one process for etching silicon the etch solution is heated by an infrared lamp. We describe the fabrication of various cantilever-based sensors, such as arrays of 0.8-μm-thick levers for a chemical/electronic nose, and 5-μm-thick silicon cantilevers having piezoresistive sensors. Our technique has good uniformity and process control and, in addition, eliminates mechanical stress on the fragile wafers incurred by wafer chucks, which are required for the conventional immersion approach. It has improved process yield and reduces the waste of chemicals. © 1998 Elsevier Science S.A. All rights reserved.

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1. Introduction

Many structures in microelectromechanical systems (MEMS) such as membranes and freestanding cantilevers require a wet-etching process on only one side of the wafer. In such a fabrication process, it is essential that the other side of the wafer and its edges are protected. In the past, individual chucks have provided this functionality by means of rubber O-ring seals on each side of the wafer, which is then immersed into the etching solution. Pressure on the chuck squeezes the two O-rings against the wafer surfaces, hence guaranteeing a good seal against the etching solution. However, the pressure applied generates substantial stress on the wafer, which is enhanced if etching takes place at temperatures different from the mounting temperature because of the difference in the thermal expansion between wafer and chuck material. Therefore, if the chucks are not properly constructed, the pressure applied to them can cause a decrease in the yield of thin membranes, which crack or break quite easily. Our low-cost approach eliminates this problem and achieves a process yield as high as that attained with more sophisticated and complex immersion types of etch chucks.

Another disadvantage of current immersion wet-etching techniques is the size of the etch apparatus needed (usually a thermostatically controlled bath) and the volume of the etchant required to cover the entire wafer chuck (typically several liters). For handling and safety reasons it would be preferable to have a smaller setup and to reduce the liquid volume to the minimum needed for etching. In addition this would be an economically appealing and environmentally friendly procedure. Of course, in mass production aimed at high-throughput parallel wafer etching, this issue is less important, but for small-scale prototype fabrication it can provide a low-cost solution to reduce the complexity of the etch apparatus as well as the waste of chemicals.

In this paper we demonstrate the use of a novel single-side wet-etch setup using a seal ring made of poly(dimethylsiloxane) (PDMS) (Dow Corning, Midland, MI) [1]. This elastomeric material has recently attracted immense interest as stamps for microcontact printing and/or micromolding in capillaries [2,3]. For our purpose, the elasticity and adhesion properties of PDMS are exploited by using it as a seal to confine an etching solution to a desired area. Here, the surface adhesion properties of PDMS allow a perfect sealing against the etchant solution without applying great pressure to the ring. After being rinsed in DI water, the PDMS rubber ring can be reused many times. With the setup described we
have been able to perform two important process steps in a MEMS fabrication sequence: (a) wet etching from one side through a silicon wafer using heated potassium hydroxide (KOH), and (b) single-side etching of a silicon-dioxide layer by buffered hydrofluoric acid (BHF).

2. PDMS seal-ring fabrication

The fabrication of a seal ring requires a replication process from a master mold machined in Teflon or another suitable material. The PDMS is mixed in a 10:1 ratio with the prepolymer components of Sylgard 184, following the recommendations of the manufacturer. Homogeneous and bubble-free mixing of the polymer is accomplished by using an automatic dispenser (Dopag, Chemn, Switzerland). Our homemade rings are formed by pouring the liquid PDMS into the master as shown in Fig. 1. The low-energy siloxane fluid fills the crevices of the master, forming a negative replica of the master mold. Cross linking of the siloxane is done by a curing process in an oven at 60°C for ~24 h. The result is an elastomeric solid that accurately retains the shape of the mold even after removal from it. Any imaginable shape of the PDMS replica is possible. For our purpose we have fabricated rings suitable for sealing the border of a 10 mm silicon wafer. The outer and inner diameters as well as the thickness of the ring are 100, 84 and 12 mm, respectively. The high chemical stability of the PDMS material allows the seal ring to be used for many kinds of wet-etching applications. No metal parts are used in the PDMS ring setup or come in contact with the etching solution. This is important for preserving good etch-rate control when using KOH because, as Hein et al. [4] have shown, metallic impurities dissolved in a KOH solution have a strong effect on the anisotropy of silicon etching.

3. Using the PDMS ring for single-side wet etching

For our purpose of single-side wet etching, the wafer is placed horizontally on a ring holder that does not touch the wafer’s active part. The PDMS ring is placed on the wafer border, establishing intimate contact with the etch mask layer over the entire ring width (about 8 mm). The excellent adhesion properties of the PDMS by its own weight are normally sufficient to provide a good seal. However, in order to ensure sealing for long etch times (>1 h), we apply light pressure between ring and wafer. This can be done by using an additional weighted ring, for instance.

The etching solution is then poured onto the surface to be etched as shown in the schematic view in Fig. 2. The ring

![Schematic illustration of the etch set-up](image)

Fig. 2. Schematic illustration of the etch set-up. The seal ring is placed on top of the wafer to be single-side etched. The adhesion between the PDMS ring and the wafer mask is sufficient to provide excellent confining of the etch solution within the ring diameter. In our case we heated the etch solution (KOH) to 60°C with an infrared heat source. The transmitted light can be used for monitoring the etch progress.
4. Microfabricating silicon structures by using the single-side wet-etch seal ring

Our new single-side, wet-etch setup has been used to fabricate a series of cantilever-based micromachined silicon sensors [6,7]. In both cases a backside etching is required locally to etch the silicon wafer to a thin membrane. In the fabrication process for piezoresistive cantilevers [7], the buried silicon-dioxide layer of the SOI wafer provides the etch stop layer. At this point of the process, the wafer’s topside is already patterned with metal, which has to be protected. Fig. 3 shows an enlargement of the etch interface. In this case, the topside must not come in contact at all with the etch solution or with any mechanical part that could damage the fragile structures. The KOH solution was renewed every 4 h to keep the etch rate at ~16 μm/h for the entire duration of the etching. The local etch rate varies within 1–2% over the wafer surface, which is mainly due to the local intensity variation of the infrared radiation. Owing to the etch-stop layer this drawback has little impact on our devices. In contrast to most conventional KOH etch techniques, the wafer is placed horizontally in the solution rather than vertically. However, we detected no significant effect on the (100) silicon etch rate. Fig. 4 demonstrates the capabilities of the new approach. It shows a through-light optical photograph of a 100 mm wafer processed using a PDMS seal ring. The silicon membrane (5 μm thick) after reaching the etch-stop layer appears light, whereas the individual chips carrying the micromechanical sensors are 400 μm thick and appear dark.

The second fabrication process for a cantilever array for electronic nose applications [6] uses an n-type silicon wafer for the sensor base and a p-doped surface layer for the cantilever beams. The backside etching of n-type silicon using 60°C, 40% KOH is controlled visually and stopped when the KOH is replenished.

![Fig. 4. Optical micrograph using a bottom-side illumination of a 100 mm silicon wafer with piezoresistive sensors processed with our etch setup. The dark and light parts show the individual chips (500 μm thick) and the thin membrane (5 μm), respectively. The silicon-dioxide interface provides good etch stop, which yields uniform membrane thickness over the entire wafer surface.](image)
infrared light begins to be transmitted through the membrane (at about 5–10 μm membrane thickness). The remaining n-silicon is then removed in an ethylenediamin-pyrocatechol (EDP) etch, which does not etch the previously structured p-doped silicon cantilevers. Fig. 5 shows the resulting array of 0.8-μm-thick cantilevers.

5. Conclusions

The PDMS seal ring has proved to be a reliable, low-cost setup for single-side wet-etching process steps. The main advantage of using the PDMS ring is that no mechanical pressure needs to be applied to seal the wafer against the etchant, which reduces the stress on the wafer and considerably improves yield. As a result of the molding process for making the PDMS ring, many geometrical shapes of the seal are feasible. Moreover, easy operation of etching and rinsing cycles make it simple to monitor the etching progress. As the wafer is not totally immersed in an etch bath, the single-side etch setup with a reduced consumption of chemicals is an economically appealing and environmentally friendly procedure for small-scale or prototype fabrication. The infrared lamp used to heat the etchant can be used to monitor the etch process via the transmission of the light through the thin membranes. For high-throughput, high-quality membrane fabrication, further improvements are necessary regarding the etch control due to fluctuation of temperature and enrichment of the etch chemicals. This could be implemented, for instance, by a circulation of fresh and temperature-controlled etching solution in order to automate this step.

Another improvement would be to implement in situ measurements of the etch rate of silicon by using a laser reflectance interferometer as demonstrated by Steinsland et al. [8].

We have found the PDMS seal ring to be very useful and versatile for various wet-etching applications where only one wafer side is allowed to come into contact with an etching solution.

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